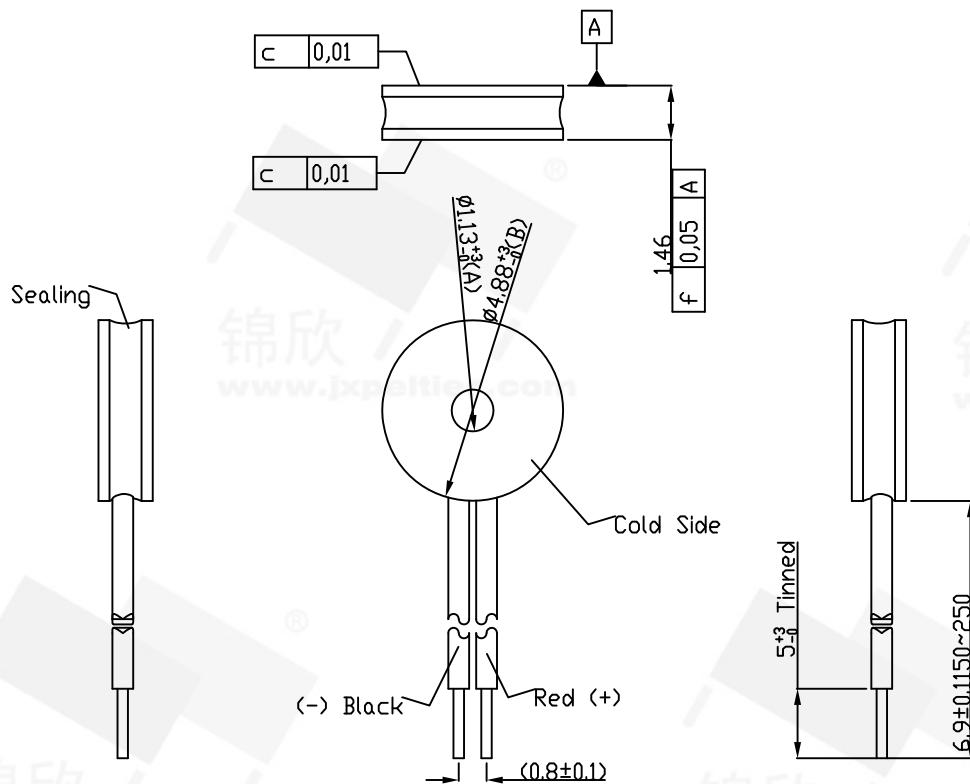
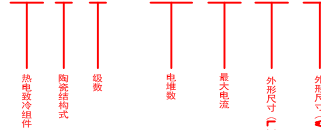


REVISIONS						
REV.	POS.	DESCRIPTION	DATE	DRW	APP	ECN#
A		INITIAL CREATION	2011/08/29	GARY	JUNSON	

TEO 1 - 017 xx 03 13



注意事项:

1. 半导体致冷片总成厚度公差为±0.2，客户在和散热片组装时，需要考量此公差带，不得压得太紧，也不能压得太松，否则会导致半导体致冷片破裂或降低功效。
2. 半导体致冷片在通电前，检查是否有安装符合要求当量的散热片，禁止空载，否则会因工作所产生热源没有传递走而烧坏。
3. 标准的半导体致冷片型号及规格参数如下列表（如有更改，不另行通知，非标规格需要定制，请联络销售部）:

序号	型号	电堆数	最大电流	最大电压	最大冷量(W)	最大温差(°C)	外形尺寸(MM)			电阻	重量
ITEM	PART NUMBER	COUPLES	A (MAX)	V (MAX)	室温环境TH=27°		A	B	H 实物为准	Ω	g
1	TEO1-017200313	17	2.0	2	2.8	67	Ø3	Ø13	3.9	-	-

*DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION



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USED OR DISCLOSED OR IN PART TO ANYONE WITHOUT THE PERMISSION OF JXPELTIER (SUZHOU)
CO., LTD.

1. UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE MM 2. TOLERANCE ARE AS FOLLOWS: 0 < X < 2 ± 0.06 2 < X < 10 ± 0.08 10 < X < 50 ± 0.12 50 < X < 100 ± 0.16 100 < X < 200 ± 0.20 200 < X < 300 ± 0.30 ANGLES ± 0.5°	Part No.	TEO1-017xx0313	DESCRIPTION	DC2.0V(Max), 1A, 017晶堆, 单层, Ø3xØ13mm			
	SIGNATURE	DATE	锦欣制冷(苏州)有限公司 JXPeltier (SUZHOU) CO., LTD Tel/Fax: +86-512-62539286 Mobile: +86-18061938176 email: jxpeltier@gmail.com http://www.jxpeltier.com				
	DRAWN BY	GARY					2011/08/29
	CHECKED BY	JACK					2011/08/29
ENGR	VIVI	2011/08/29					
APPROVED BY	JASON	2011/08/29	CAD MODEL	SCALE: 1:1	REV: A		
MATERIAL:	ISSUED BY	LILY	2011/08/29	CAD DWG	SIZE: A3	SHEET: 1 OF 1	